



## Material Content Data Sheet



<b>Sales Product Name</b>		TLE9278-3BQX V33		<b>Issued</b>		31. January 2019		
<b>MA#</b>		MA003625824						
<b>Package</b>		PG-VQFN-48-31		<b>Weight*</b>		129.86 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.524	3.48	3.48	34839	34839
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
		non noble metal	zinc	7440-66-6	0.072	0.06		552
		non noble metal	iron	7439-89-6	1.433	1.10		11036
wire	non noble metal	copper	7440-50-8	58.193	44.82	45.99	448115	459841
		copper	7440-50-8	0.572	0.44	0.44	4404	4404
encapsulation	organic material	carbon black	1333-86-4	0.182	0.14		1402	
		plastics	epoxy resin	-	7.706	5.93		59338
		inorganic material	silicondioxide	60676-86-0	52.787	40.65	46.72	406485
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	19993	19993
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4727	4727
glue	plastics	epoxy resin	-	0.268	0.21		2063	
		noble metal	silver	7440-22-4	0.897	0.69	0.90	6908
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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